

In the Claims

Claims 1 and 2 (canceled).

- 1 3. (new) A method for simultaneously molding a plurality of
2 semiconductor chips, comprising the following steps:
- 3 a) securing said plurality of semiconductor chips with a
4 first chip surface to a substrate so that spaces are
5 provided between neighboring semiconductor chips on
6 said substrate;
- 7 b) inserting said substrate with said semiconductor chips
8 thereon into a mold portion (2);
- 9 c) covering a second chip surface facing opposite said
10 first chip surface of said plurality of semiconductor
11 chips with a mold release film;
- 12 d) simultaneously and individually applying equal
13 pressure to all of said second chip surfaces of said
14 plurality of semiconductor chips so that each said
15 second chip surface is fully covered by said mold
16 release film, and so that gaps between said second
17 chip surfaces and said mold release film are avoided;
- 18 e) closing said mold portion, except for a resin feed-in
19 gate (19), to form a mold cavity between said mold
20 release film and said substrate, whereby said
21 plurality of semiconductor chips is enclosed in said
22 mold cavity;
- 23 f) filling said mold cavity between said substrate and
24 said mold release film with resin;

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- 25 g) letting said resin set to form a molding (38) with
26 said plurality of semiconductor chips held in place on
27 said substrate by said resin; and
28 h) opening said mold and removing said molding (38) from
29 said mold portion.

1 4. (new) The method of claim 3, further comprising the step of
2 cutting said molding for separating said plurality of
3 semiconductor chips to form individual molded semiconductor
4 chips.

1 5. (new) The method of claim 3, further comprising holding
2 down said substrate by clamping an intermediate mold member
3 against a peripheral portion (41) of said substrate.

1 6. (new) The method of claim 3, further comprising performing
2 said step of simultaneously and individually applying equal
3 pressure to said second chip surfaces of said semiconductor
4 chips in a resilient manner for accommodating different
5 chip heights and different second chip surface formations.

1 7. (new) The method of claim 3, further comprising tensioning
2 said mold release film in a direction in a plane defined by
3 said mold release film.

1 8. (new) The method of claim 3, further comprising using a
2 three part mold (1, 2, 3) for clamping said mold release
3 film (4) between a first mold part (1) and a second mold
4 part (3), resting against a third part formed by said mold
5 portion (2).

1 9. (new) An apparatus for simultaneously molding a plurality
2 of semiconductor chips, said apparatus comprising means for
3 performing steps a) to h) as defined in claim 3.

[RESPONSE CONTINUES ON NEXT PAGE]

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